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# DATA SHEET

## **74F174** Hex D flip-flops

Product specification

1988 Oct 07

IC15 Data Handbook

# Hex D flip-flop

# 74F174

## FEATURES

- Six edge-triggered D-type flip-flops
- Buffered common Clock
- Buffered, asynchronous Master Reset

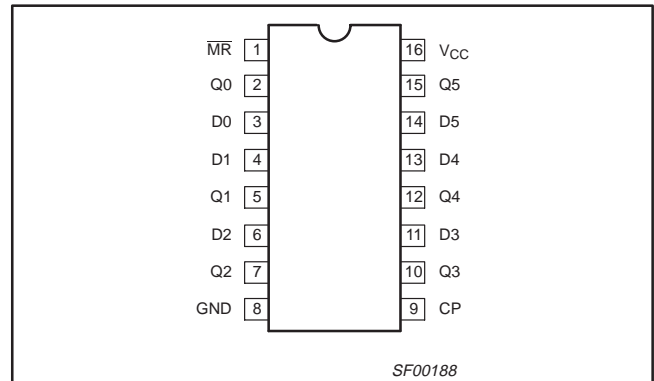
## DESCRIPTION

The 74F174 has six edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset ( $\overline{MR}$ ) inputs load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the Low-to-High clock transition is transferred to the corresponding flip-flop's Q output.

All Q outputs will be forced Low independent of Clock or Data inputs by a Low voltage level on the  $\overline{MR}$  input. The device is useful for applications where true outputs only are required, and the Clock and Master Reset are common to all storage elements.

## PIN CONFIGURATION



TYPE	TYPICAL $f_{MAX}$	TYPICAL SUPPLY CURRENT (TOTAL)
74F174	100MHz	35mA

## ORDERING INFORMATION

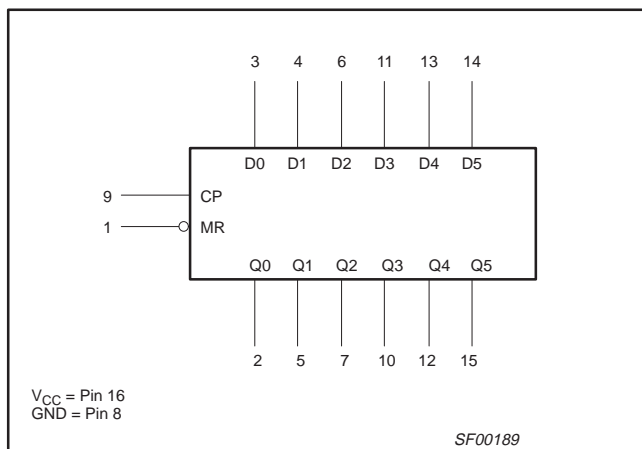
DESCRIPTION	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$ , $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$	PKG DWG #
16-pin plastic DIP	N74F174N	SOT38-4
16-pin plastic SO	N74F174D	SOT109-1

## INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

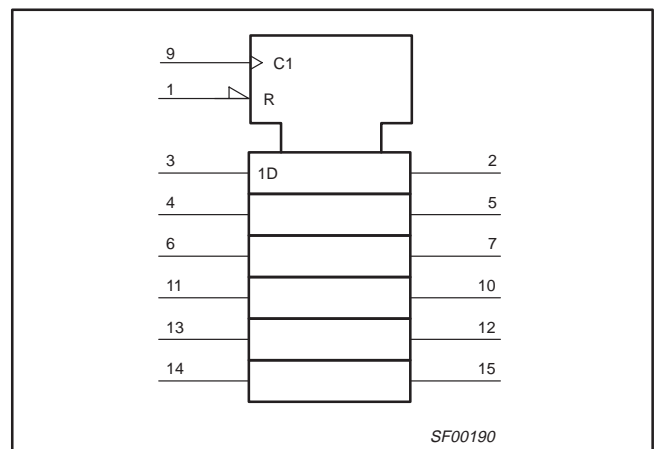
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0–D5	Data inputs	1.0/1.0	20 $\mu$ A/0.6mA
CP	Clock Pulse input (active rising edge)	1.0/1.0	20 $\mu$ A/0.6mA
$\overline{MR}$	Master Reset input (active-Low)	1.0/1.0	20 $\mu$ A/0.6mA
Q0–Q5	Outputs	50/33	1.0mA/20mA

**NOTE:** One (1.0) FAST unit load is defined as: 20 $\mu$ A in the High state and 0.6mA in the Low state.

## LOGIC SYMBOL



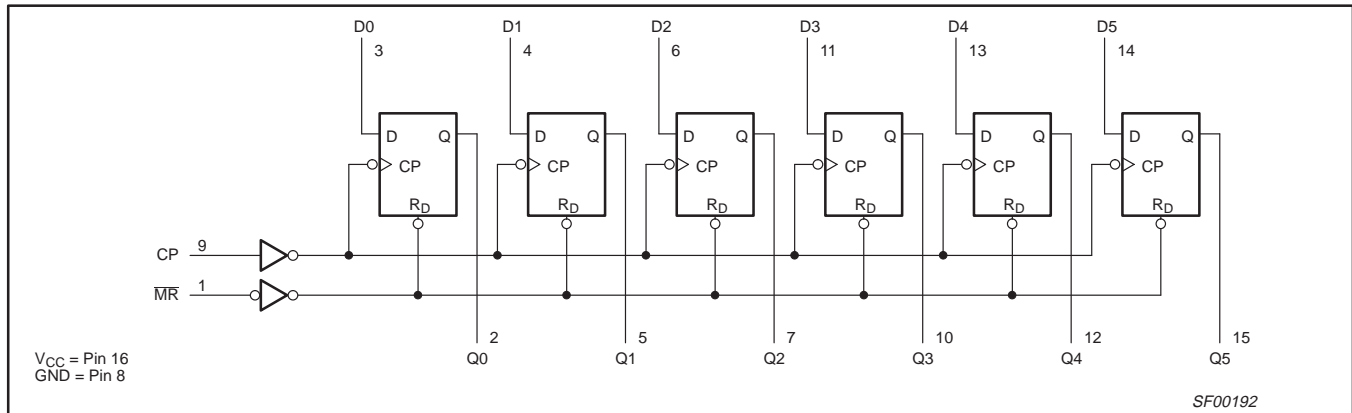
## IEC/IEEE SYMBOL



# Hex D flip-flop

74F174

## LOGIC DIAGRAM



## FUNCTION TABLE

INPUTS			OUTPUTS	OPERATING MODE
MR	CP	D	Qn	
L	X	X	L	Reset (clear)
H	↑	h	H	Load "1"
H	↑	l	L	Load "0"

H = High voltage level

L = Low voltage level

X = Don't care

↑ = Low-to-High Clock transition

h = High voltage level one set-up time prior to the Low-to-High Clock transition.

l = Low voltage level one set-up time prior to the Low-to-High Clock transition.

## ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device.

Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	-0.5 to V <sub>CC</sub>	V
I <sub>OUT</sub>	Current applied to output in Low output state	40	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C

## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS			UNIT
		MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage	2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>IK</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-1	mA
I <sub>OL</sub>	Low-level output current			20	mA
T <sub>amb</sub>	Operating free-air temperature range	0		+70	°C

## Hex D flip-flop

74F174

**DC ELECTRICAL CHARACTERISTICS**

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS <sup>1</sup>	LIMITS			UNIT		
			MIN	TYP <sup>2</sup>	MAX			
V <sub>OH</sub>	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX	±10%V <sub>CC</sub>	2.5		V		
		V <sub>IH</sub> = MIN, I <sub>OH</sub> = MAX	±5%V <sub>CC</sub>	2.7	3.4			
V <sub>OL</sub>	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX	±10%V <sub>CC</sub>		0.30	0.50	V	
		V <sub>IH</sub> = MIN, I <sub>OL</sub> = MAX	±5%V <sub>CC</sub>		0.30	0.50		
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>I</sub> = I <sub>IK</sub>			-0.73	-1.2	V	
I <sub>I</sub>	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7.0V				100	μA	
I <sub>IH</sub>	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7V				20	μA	
I <sub>IL</sub>	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5V				-0.6	mA	
I <sub>OS</sub>	Short-circuit output current <sup>3</sup>	V <sub>CC</sub> = MAX			-60	-150	mA	
I <sub>CC</sub>	Supply current (total)	V <sub>CC</sub> = MAX, D <sub>n</sub> = $\overline{MR}$ = 4.5V, CP = ↑				35	45	mA

**NOTES:**

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
- Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

**AC ELECTRICAL CHARACTERISTICS**

SYMBOL	PARAMETER	TEST CONDITION	LIMITS					UNIT
			V <sub>CC</sub> = +5.0V T <sub>amb</sub> = +25°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω			V <sub>CC</sub> = +5.0V ± 10% T <sub>amb</sub> = 0°C to +70°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω		
			MIN	TYP	MAX	MIN	MAX	
f <sub>MAX</sub>	Maximum clock frequency	Waveform 1	80	100		80		MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CP to Q <sub>n</sub>	Waveform 1	3.5 4.5	5.5 6.0	8.0 10.0	3.5 4.5	9.0 11.0	ns
t <sub>PHL</sub>	Propagation delay $\overline{MR}$ to Q <sub>n</sub>	Waveform 2	5.0	8.5	14.0	5.0	15.0	ns

**AC SETUP REQUIREMENTS**

SYMBOL	PARAMETER	TEST CONDITION	LIMITS					UNIT
			V <sub>CC</sub> = +5.0V T <sub>amb</sub> = +25°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω			V <sub>CC</sub> = +5.0V ± 10% T <sub>amb</sub> = 0°C to +70°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω		
			MIN	TYP	MAX	MIN	MAX	
t <sub>S</sub> (H) t <sub>S</sub> (L)	Setup time, High or Low D <sub>n</sub> to CP	Waveform 3	4.0 4.0			4.0 4.0		ns
t <sub>H</sub> (H) t <sub>H</sub> (L)	Hold time, High or Low D <sub>n</sub> to CP	Waveform 3	0.0 0.0			0.0 0.0		ns
t <sub>w</sub> (H) t <sub>w</sub> (L)	CP Pulse width, High or Low	Waveform 1	4.0 6.0			4.0 6.0		ns
t <sub>w</sub> (L)	$\overline{MR}$ Pulse width, Low	Waveform 2	5.0			5.0		ns
t <sub>REC</sub>	Recovery time, $\overline{MR}$ to CP	Waveform 2	5.0			5.0		ns

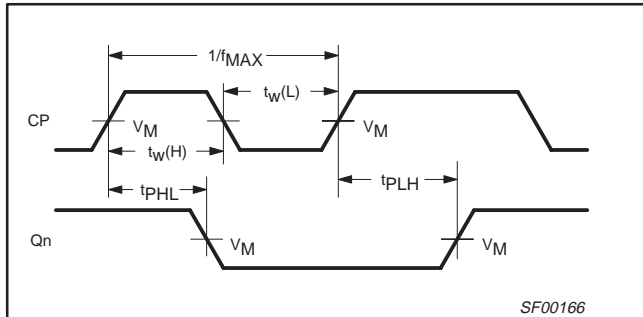
# Hex D flip-flop

74F174

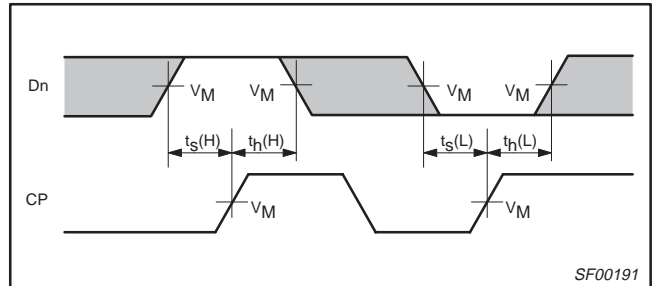
## AC WAVEFORMS

For all waveforms,  $V_M = 1.5V$ .

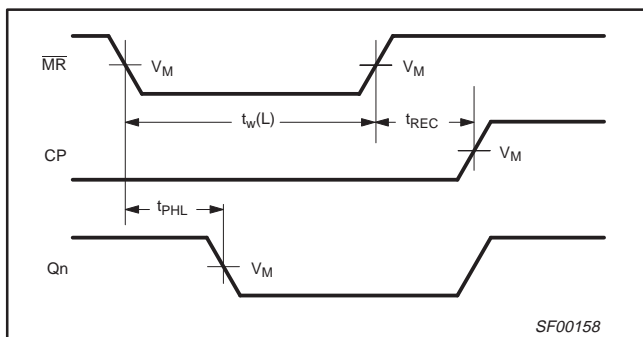
The shaded areas indicate when the input is permitted to change for predictable output performance.



**Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency**

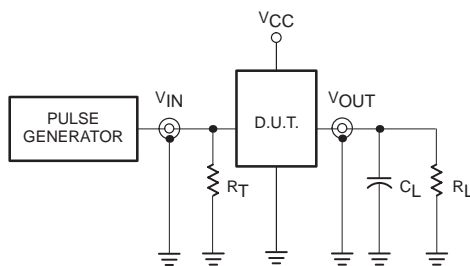


**Waveform 3. Data Setup and Hold Times**

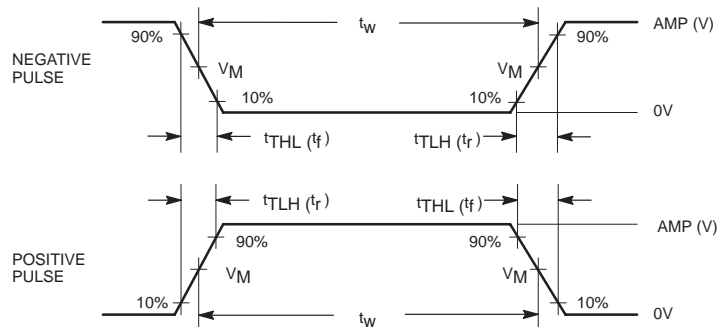


**Waveform 2. Master Reset Pulse Width, Master Reset to Output Delay and Master Reset to Clock recovery Time**

## TEST CIRCUIT AND WAVEFORMS



**Test Circuit for Totem-Pole Outputs**



**Input Pulse Definition**

### DEFINITIONS:

- $R_L$  = Load resistor; see AC ELECTRICAL CHARACTERISTICS for value.
- $C_L$  = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.
- $R_T$  = Termination resistance should be equal to  $Z_{OUT}$  of pulse generators.

family	INPUT PULSE REQUIREMENTS					
	amplitude	$V_M$	rep. rate	$t_w$	$t_{TLH}$	$t_{THL}$
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

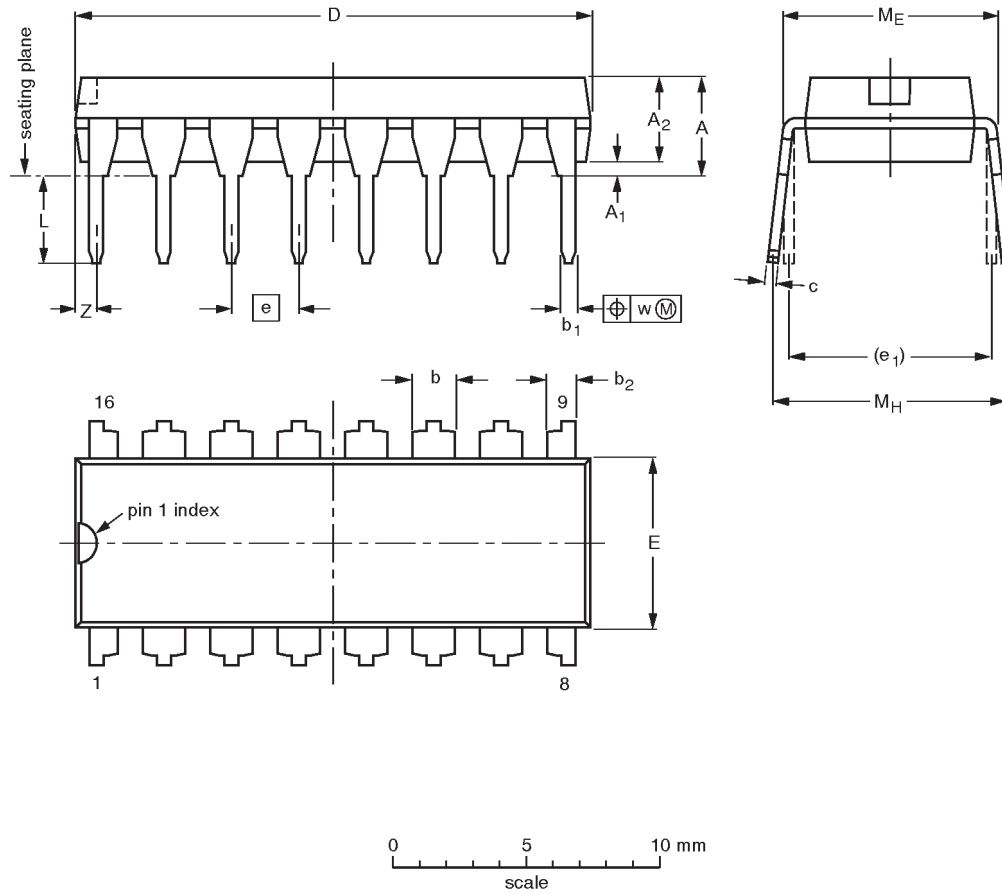
SF00006

# Hex D flip-flops

74F174

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

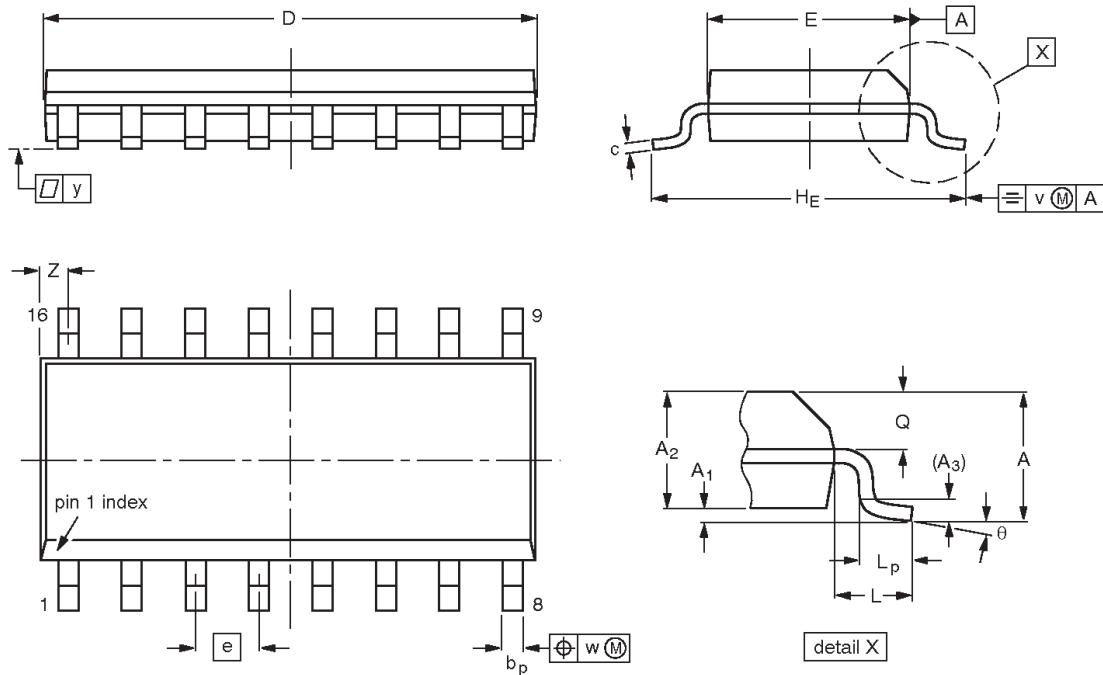
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT38-4						92-11-17 95-01-14

# Hex D flip-flops

74F174

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

**Note**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT109-1	076E07S	MS-012AC				95-01-23 97-05-22



## Hex D flip-flops

74F174

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